

EPC Space Model Report: EPC7014		
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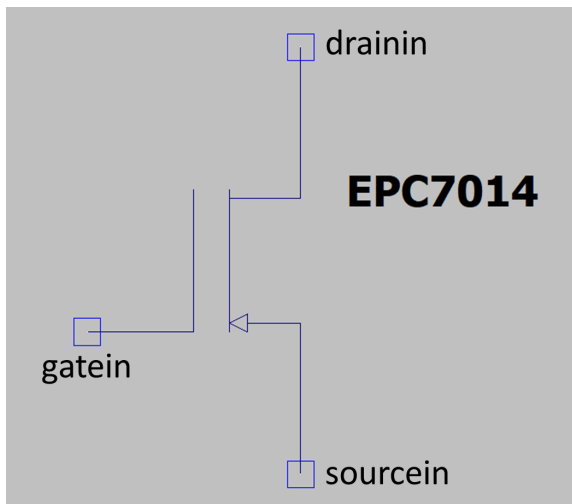
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2. Symbol

2.1. Summary

The model package includes a generic symbol as shown below.

Figure 2.1-1 Generic SPICE symbol.



The symbol generates a netlist entry with pin order D G S. No additional parameters are necessary, but users can pass their own values for the parameters defined in this model report.

3. Model

3.1. Summary

The EPC Space model contains the sub-circuit shown below.

Figure 3.1-1 EPC Space Model.

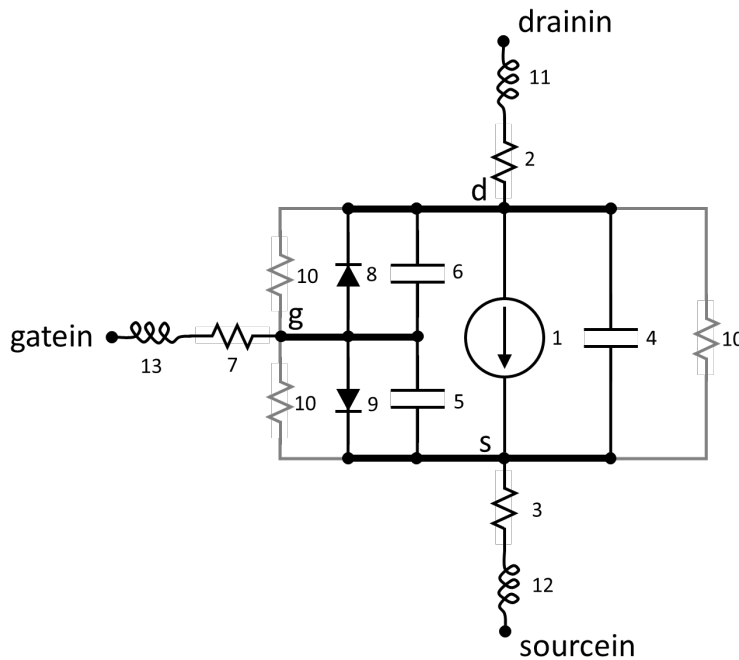


Table 3.1-1. Sub-circuit component definitions.

#	Name	Description
1	$I(V_g, V_d, V_s)$	Channel
2	R_d	Drain-side parasitic resistance
3	R_s	Source-side parasitic resistance
4	$C_{ds}(V_d, V_s)$	Drain-source capacitance
5	$C_{gs}(V_g, V_s)$	Gate-source capacitance
6	$C_{gd}(V_g, V_d)$	Gate-drain capacitance
7	R_g	Gate resistance
8	$I(V_g, V_d)$	Gate-drain leakage
9	$I(V_g, V_s)$	Gate-source leakage
10	R_{conv}	Convergence aid ($\sim G\Omega$)
11	L_d	Drain-side inductance
12	L_s	Source-side inductance
13	L_g	Gate-side inductance

The known limitations of the model are as follows:

- Based on measurements between 25 and 150 °C.
- Gate leakages are not based on data and are modeled as unidirectional.

4. EPC7014 Model

4.1. Model Parameters

Model parameters are listed below along with their default (typical) values and suggested ranges.

Table 4.1-1. Model Parameters.

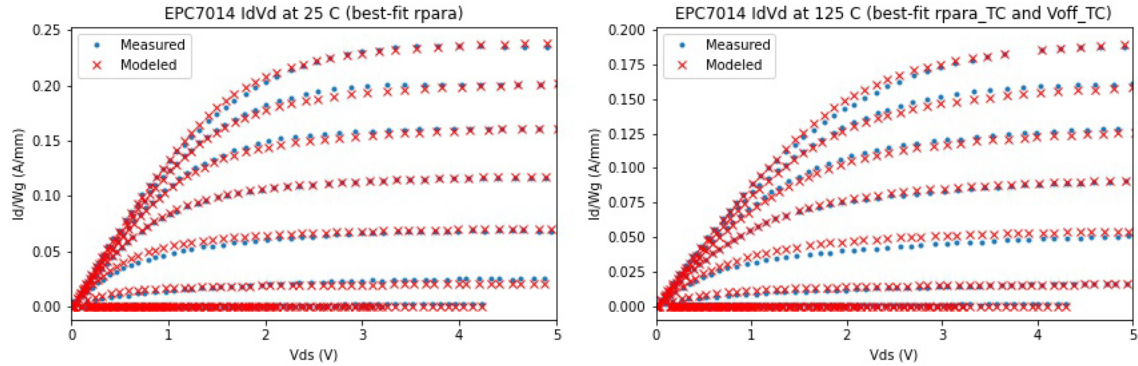
Parameter	Units	Description	Typical	Fast	Slow	Source of F/S param.
<i>aWg</i>	mm	Gate width	27			
<i>A1</i>	S/mm	Normalized peak transconductance	0.1425	0.1453	0.1399	Observed variation
<i>Voff</i>	V	Threshold voltage	2.33	1.50	3.20	DS limits
<i>rpara</i>	Ω	Total chip scale parasitic resistance	0.224	0.20	0.249	Observed variation
<i>Vdsat</i>	V	<i>Vds</i> where output curves transition to saturation	0.315			
<i>ua</i>	V ⁻¹	Coefficient of mobility degradation with vertical electric field	0.144	0.151	0.138	Observed variation
<i>Vgshape</i>	V	Overdrive voltage effect on <i>Vdsat</i>	4.02			
<i>k3</i>	V	Sub-threshold swing parameter	0.09			
<i>rpara_s_factor</i>	(none)	Fraction of the chip scale parasitic resistance on the source side	0.215			
<i>rg_value</i>	Ω	Gate Resistance	12.6			
<i>pack_indd</i>	H	Drain-side inductance	3.55E-09			
<i>pack_inds</i>	H	Source-side inductance	3.55E-09			
<i>pack_indg</i>	H	Gate-side inductance	4.40E-09			
<i>pack_rd</i>	Ω	Additional drain-side resistance from packaging	5.65E-02			
<i>pack_rs</i>	Ω	Additional source-side resistance from packaging	5.65E-02			
<i>pack_rg</i>	Ω	Additional gate-side resistance from packaging	0.0			
<i>A1_TC</i>	K ⁻¹	Temp.-co. of <i>A1</i>	1.70E-03	1.93E-03	1.47E-03	Observed variation
<i>Voff_TC</i>	K ⁻¹	Temp.-co. of <i>Voff</i>	8.93E-04	1.93E-03	-1.41E-04	Observed variation
<i>Vdsat_TC</i>	K ⁻¹	Temp.-co. of <i>Vdsat</i>	3.59E-02	6.85E-02	3.19E-03	Observed variation
<i>rpara_TC</i>	K ⁻¹	Temp.-co. of <i>rpara</i>	-7.58E-03	-8.16E-03	-7.00E-03	Observed variation
<i>Vgshape_TC</i>	K ⁻¹	Temp.-co. of <i>Vgshape</i>	-2.88E-03	-3.51E-03	-2.25E-03	Observed variation
<i>cgs0</i>	F/mm	Voltage-independent gate-source capacitance	5.25E-13	5.11E-13	5.39E-13	Observed variation
<i>cgs_a</i>	F/mm	Amplitude of voltage-dependent gate-source capacitance	3.27E-13			
<i>cgs_av</i>	V	Location in voltage space of voltage-	2.098	1.3	3	DS Limits

Parameter	Units	Description	Typical	Fast	Slow	Source of F/S param.
		dependent capacitance				
<i>cgs_aw</i>	V	Transition width of voltage-dependent capacitance	0.29317			
<i>cgd0</i>	F/mm	Voltage-independent gate-drain capacitance	1.94E-15			
<i>cgd_a</i>	F/mm	Amplitude of voltage-dependent gate-drain capacitance	1.18E-13			
<i>cgd_av</i>	V	Location in voltage space of voltage-dependent capacitance	-5			
<i>cgd_aw</i>	V	Transition width of voltage-dependent capacitance	4.314			
<i>cgd_b</i>	F/mm	Amplitude of voltage-dependent gate-drain capacitance	7.79E-15			
<i>cgd_bv</i>	V	Location in voltage space of voltage-dependent capacitance	-17.26			
<i>cgd_bw</i>	V	Transition width of voltage-dependent capacitance	15.29			
<i>csd0</i>	F/mm	Voltage-independent drain-source capacitance	2.61E-13			
<i>csd_a</i>	F/mm	Amplitude of voltage-dependent drain-source capacitance	4.78E-13			
<i>csd_av</i>	V	Location in voltage space of voltage-dependent capacitance	-13.35			
<i>csd_aw</i>	V	Transition width of voltage-dependent capacitance	1.2066			
<i>csd_b</i>	F/mm	Amplitude of voltage-dependent drain-source capacitance	7.59E-13			
<i>csd_bv</i>	V	Location in voltage space of voltage-dependent capacitance	-30.14			
<i>csd_bw</i>	V	Transition width of voltage-dependent capacitance	47.927			
<i>dgs1</i>	A/mm	Gate leakage prefactor	4.3E-07			
<i>dgs2</i>	A/mm	Gate leakage prefactor	2.6E-13			
<i>dgs3</i>	V	Gate leakage bias dependence parameter	0.8			
<i>dgs4</i>	V	Gate leakage bias dependence parameter	0.23			

Parameters ranges set according to observed variation come from fitting the slow corner device, with 7.6% higher $R_{ds(on)}$. No fast device was measured, parameters are assumed to be symmetrical for slow and fast corners.

4.2. Parameter Extraction

Figure 4.2-1 DC IdVd, Typical, 25 and 150 deg C.



Models will not exactly reproduce the curves shown above, because final models account for additional properties such as the effect of packaging.